



4A, 600V N-CHANNEL MOSFET

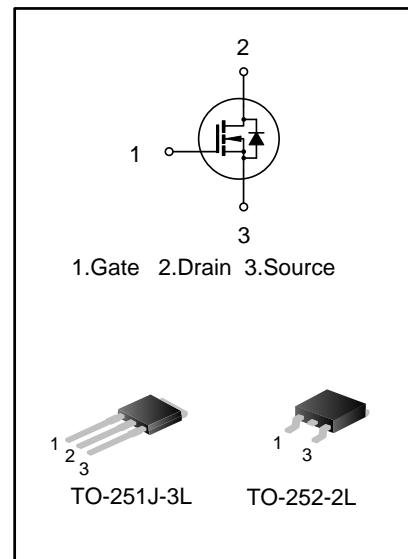
GENERAL DESCRIPTION

SVFP4N60CAMJ/D is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ high-voltage planar VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

FEATURES

- 4A, 600V, $R_{DS(on)(typ.)}=2.0\Omega$ @ $V_{GS}=10V$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVFP4N60CAMJ	TO-251J-3L	P4N60CAMJ	Halogen free	Tube
SVFP4N60CADTR	TO-252-2L	P4N60CAD	Halogen free	Tape&Reel



ABSOLUTE MAXIMUM RATINGS (T_A=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Ratings		Unit
		SVFP4N60CAMJ	SVFP4N60CAD	
Drain-Source Voltage	V _{DS}	600		V
Gate-Source Voltage	V _{GS}	±30		V
Drain Current	T _C =25°C	I _D	4.0	A
	T _C =100°C		2.5	
Drain Current Pulsed	I _{DM}	16		A
Power Dissipation(T _C =25°C) -Derate above 25°C	P _D	86	77	W
		0.69	0.62	W/°C
Single Pulsed Avalanche Energy(Note1)	E _{AS}	217		mJ
Reverse Diode dv/dt (Note 2)	dv/dt	4.5		V/ns
MOSFET dv/dt Ruggedness (Note 3)	dv/dt	50		V/ns
Operation Junction Temperature Range	T _J	-55~+150		°C
Storage Temperature Range	T _{stg}	-55~+150		°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings		Unit
		SVFP4N60CAMJ	SVFP4N60CAD	
Thermal Resistance,Junction-to-Case	R _{θJC}	1.45	1.61	°C/W
Thermal Resistance,Junction-to-Ambient	R _{θJA}	62.0	62.0	°C/W



ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	600	--	--	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2.0	--	4.0	V
Static Drain- Source On State Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2.0\text{A}$	--	2.0	2.4	Ω
Input Capacitance	C_g	$f=1.0\text{MHz}$	--	3.6	--	Ω
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	--	433	--	pF
Output Capacitance	C_{oss}		--	55	--	
Reverse Transfer Capacitance	C_{rss}		--	4.5	--	
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=300\text{V}, I_{\text{D}}=4\text{A}, R_{\text{G}}=25\Omega$ (Note 4,5)	--	10	--	ns
Turn-on Rise Time	t_r		--	26	--	
Turn-off Delay Time	$t_{\text{d(off)}}$		--	29	--	
Turn-off Fall Time	t_f		--	26	--	
Total Gate Charge	Q_g	$V_{\text{DS}}=480\text{V}, I_{\text{D}}=4\text{A}, V_{\text{GS}}=10\text{V}$ (Note 4,5)	--	13	--	nC
Gate-Source Charge	Q_{gs}		--	2.8	--	
Gate-Drain Charge	Q_{gd}		--	6.2	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

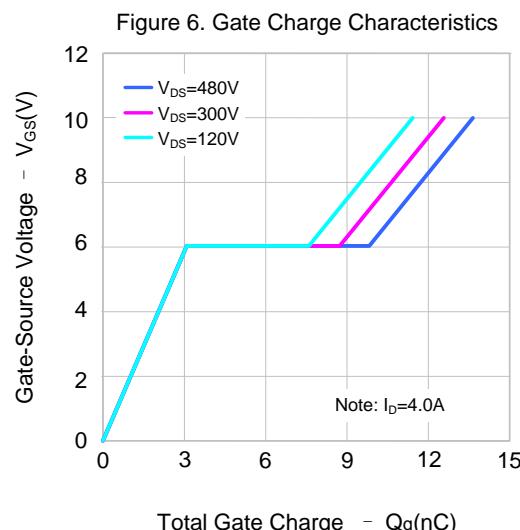
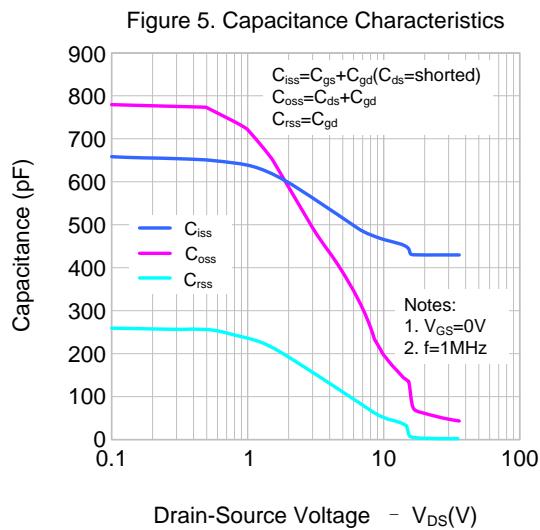
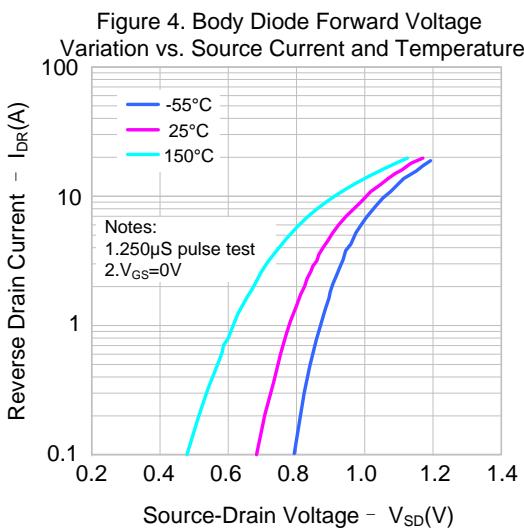
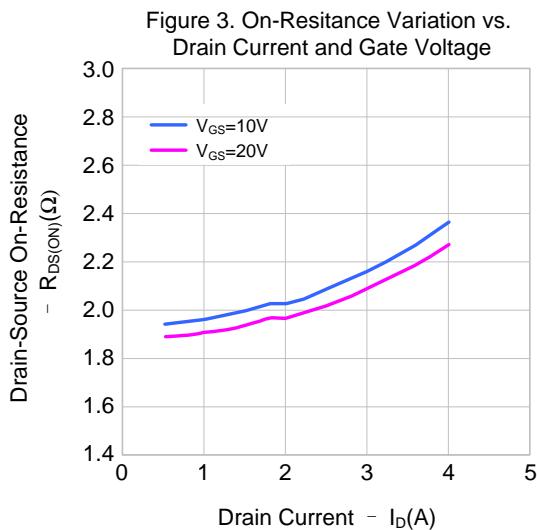
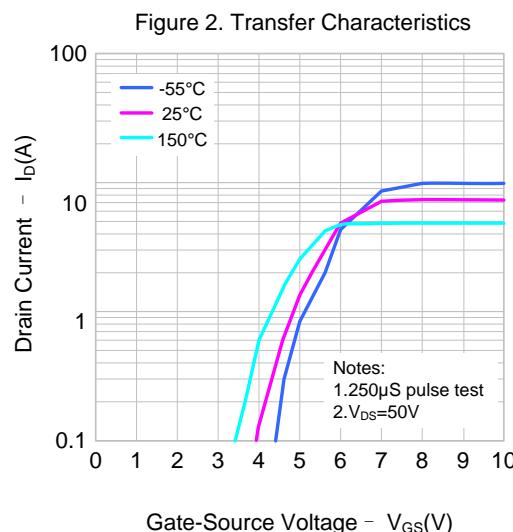
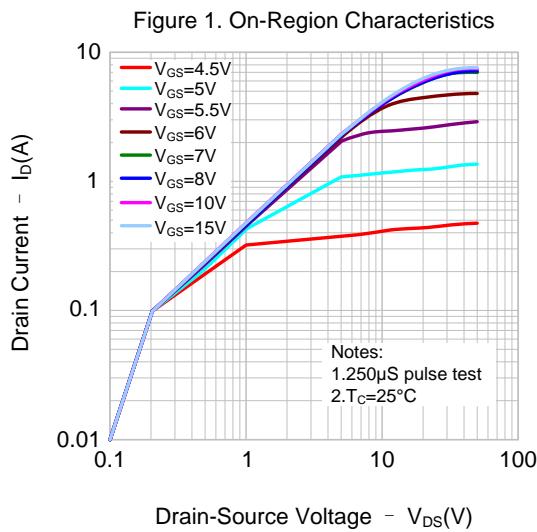
Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_s	Integral Reverse P-N Junction Diode in the MOSFET	--	--	4.0	A
Pulsed Source Current	I_{SM}		--	--	16	
Diode Forward Voltage	V_{SD}	$I_s=4.0\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$I_s=4.0\text{A}, V_{\text{GS}}=0\text{V},$ $dI_F/dt=100\text{A}/\mu\text{s}$ (Note 4)	--	420	--	ns
Reverse Recovery Charge	Q_{rr}		--	1.8	--	μC

Notes:

1. $L=30\text{mH}, I_{\text{AS}}=3.75\text{A}, V_{\text{DD}}=100\text{V}, R_{\text{G}}=25\Omega$, starting temperature $T_J=25^\circ\text{C}$;
2. $V_{\text{DS}}=0\sim 400\text{V}, I_{\text{SD}} \leq 4\text{A}, T_J=25^\circ\text{C}$;
3. $V_{\text{DS}}=0\sim 480\text{V}$;
4. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$;
5. Essentially independent of operating temperature.



TYPICAL CHARACTERISTICS





TYPICAL CHARACTERISTICS(CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

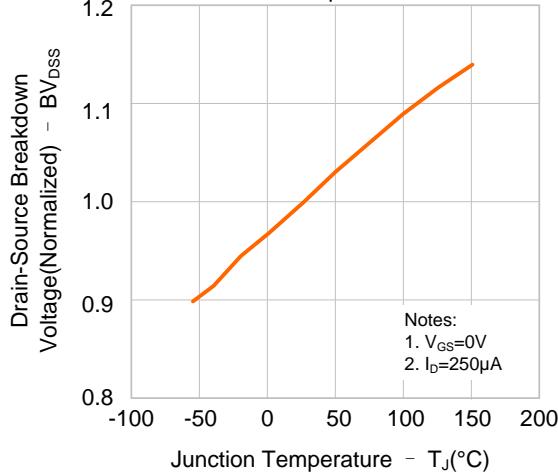


Figure 8. On-resistance Variation vs. Temperature

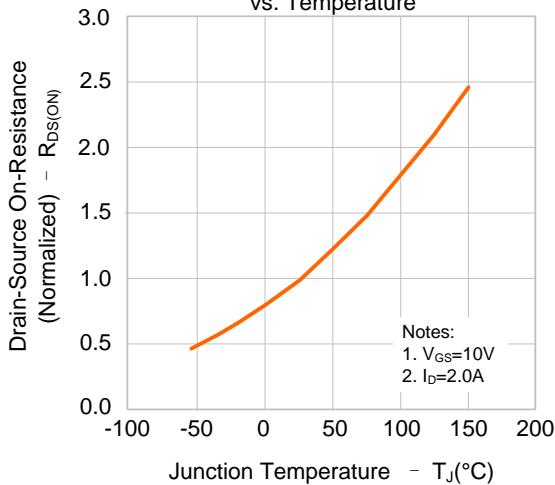


Figure 9-1. Max. Safe Operating Area (SVFP4N60CAMJ)

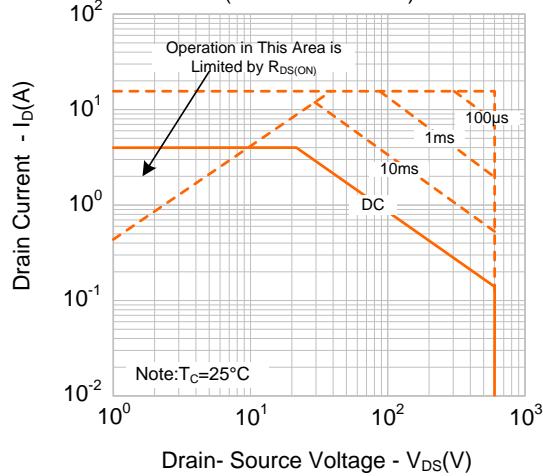


Figure 9-2. Max. Safe Operating Area (SVFP4N60CAD)

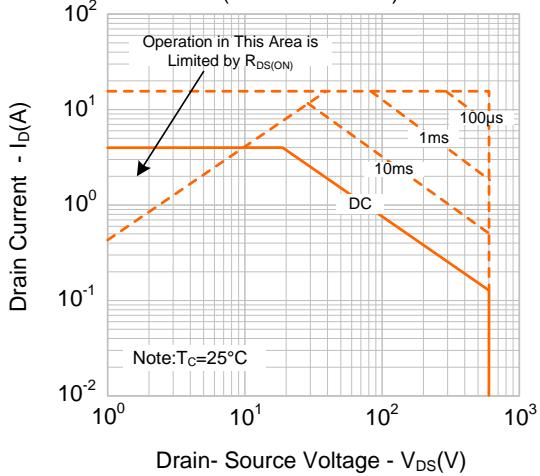
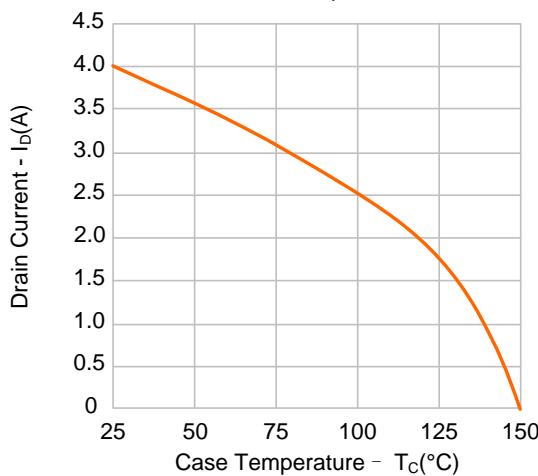
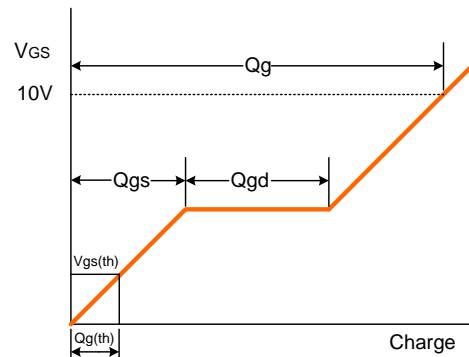
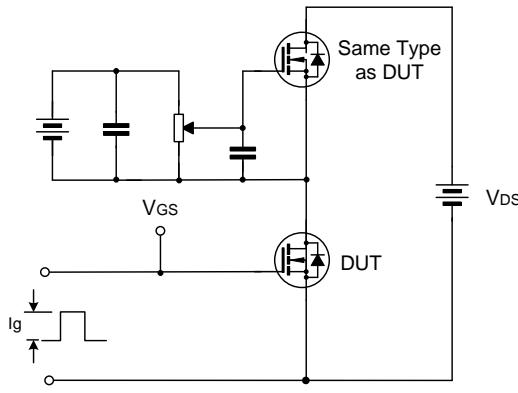


Figure 10. Maximum Drain Current vs. Case Temperature

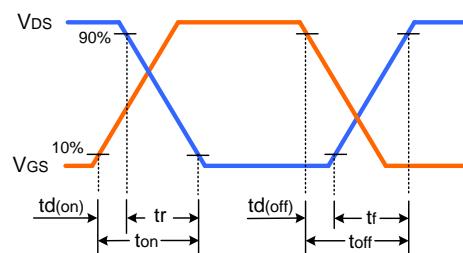
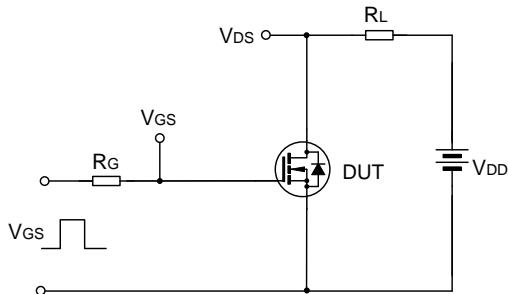




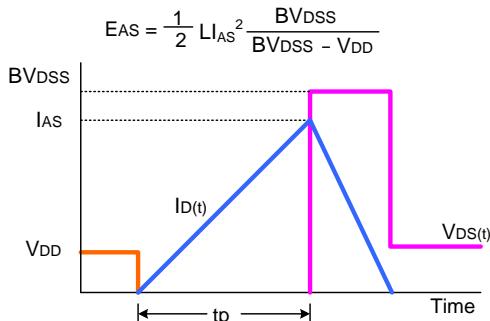
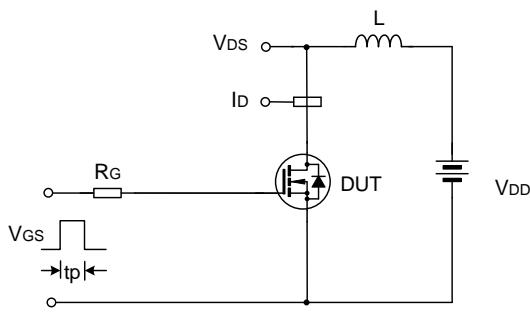
TYPICAL TEST CIRCUIT



Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



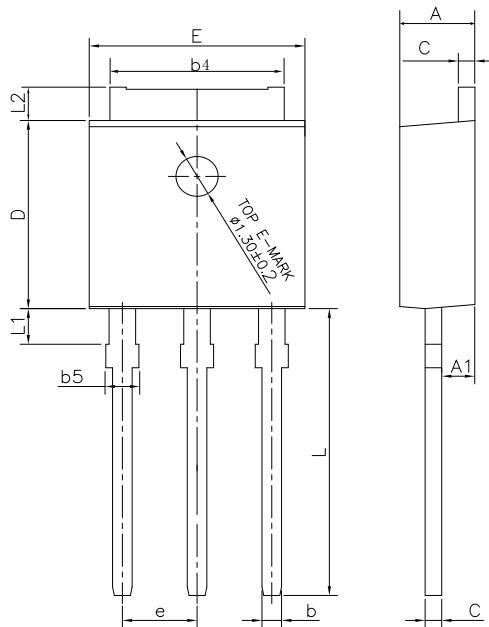
Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE

TO-251J-3L

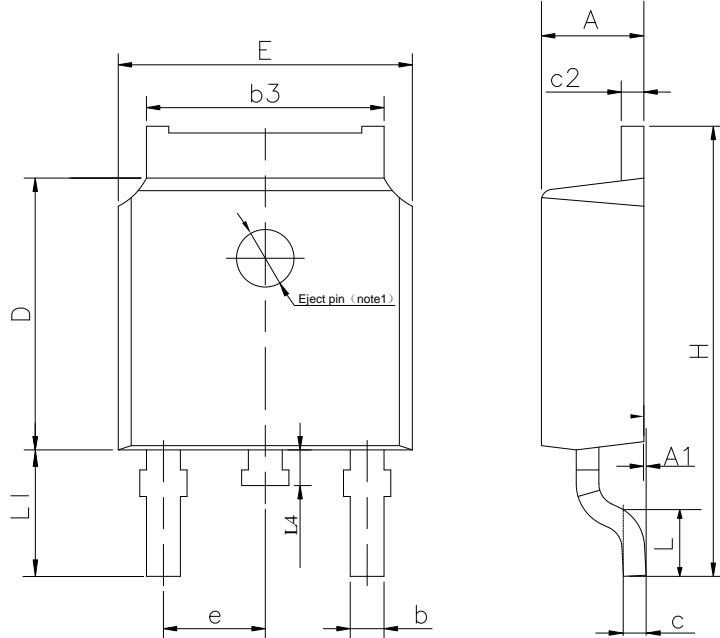
UNIT: mm



SYMBOL	MIN	NOM	MAX
A	2.18	2.30	2.39
A1	0.89	1.00	1.14
b	0.56	---	0.89
b4	4.95	5.33	5.46
b5	---	---	1.05
c	0.46	---	0.61
D	5.97	6.10	6.27
E	6.35	6.60	6.73
e	2.29 BCS		
L	8.89	9.30	9.65
L1	0.95	---	1.50
L2	0.89	---	1.27

TO-252-2L

UNIT: mm



SYMBOL	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	---	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	---	0.65
c2	0.45	---	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

NOTE1 : There are two conditions for this position:has an eject pin or has no eject pin.

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- The instructions are subject to change without notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- Our products are consumer electronic products, and / or civil electronic products.
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- Product promotion is endless, our company will wholeheartedly provide customers with better products!
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Part No.: **SVFP4N60CAMJ/D**

Document Type: **Datasheet**

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Rev.: **1.2**

Revision History:

1. Modify Electrical schematic and TYPICAL TEST CIRCUIT
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Rev.: **1.1**

Revision History:

1. Add TO-252-2L
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Rev.: **1.0**

Revision History:

1. First release
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